

Special Issue

Reliability and Engineering Applications

Message from the Guest Editors

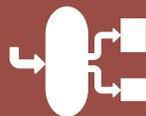
Reliable processes are critical in various fields including chemical, mechanical, electrical, material, and biomedical engineering with various scales from nano to macro. This Special Issue aims to provide insights for researchers to discuss recent advanced reliable processes and techniques, and applications to address many challenging engineering problems. Unique and novel manufacturing, modeling, and numerical methods of any industrial applications are of special interest.

Guest Editors

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Dr. Jong-Won Park
Dr. Sunghan Kim

Deadline for manuscript submissions

closed (25 March 2023)



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Editor-in-Chief

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